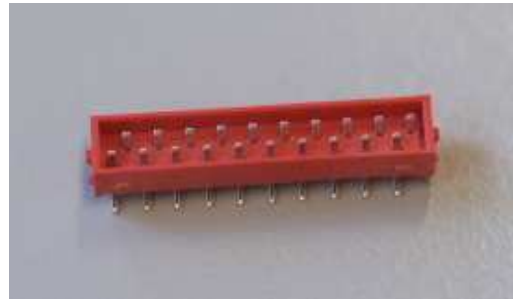
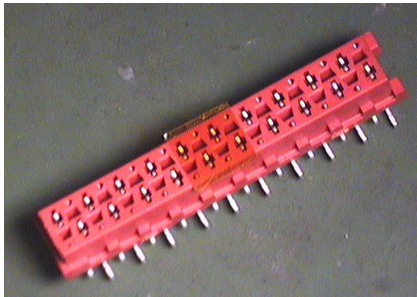


Job Number E04.07.01	Project Number: 770002	Date of issue: May 2005
Description: MicroMatch Resistance to lead-free reflow soldering heat		Part numbers: 9-188275-0 rev. U (Female on Board) 9-0338728-0 rev. U (Male on board)

Scope:

To verify resistance to soldering heat for lead-free reflow soldering.

**Conclusions:**

No detrimental effects or visual aspects were found after exposure to a temperature profile with a peak temperature of 260 °C.

Note: this report is valid for all reflow soldered Micro Match products.

Test Specification: Product Specification 108-19052 Rev. E.
Tyco Test-Spec. 109-201, Rev. B

Test Carried Out: 1 Exposure to soldering heat
2 Visual inspection
3

Distribution: 1 R. Verbeet
2 Doc. center
3 File Lab.

Test Engineer: H. van Oosterhout

Requested by: R. Verbeet

Laboratory Manager: D.M.J. Jooren.

Classification: Unrestricted

Disposal of Samples: Destroyed

Report Number: 501-19092 | Rev. O

Appendices:

Page 1 of 2 Pages

SAMPLE DESCRIPTION

10 Female on board connectors,
10 Male on board connectors.

TEST PROCEDURES

Tyco 109-201,
§3.4. B.2.

Resistance to soldering heat:

The samples were 3 times subjected to the following temperature profile:

Preheat average ramp rate : 3 °C / s
Preheat temperature (minimum) : 150 °C
Preheat temperature (maximum) : 200 °C
Preheat time : 60 to 180 s
Ramp to peak : 3 °C / s
time over liquidus (217 °C) : 60 to 150 s
Tpeak : 260 +0/-5 °C
time within 5 deg C of peak : 20 to 40 s
Ramp - cool down : 6 °C / s
time to peak : 8 min

The tests were performed in an infrared reflow oven, the samples were shielded from direct impingement of the infrared radiation

IEC 60512-1-1:
Test 1a

VISUAL EXAMINATION

The test samples were visually inspected under a stereomicroscope, at a 10x magnification, with suitable illumination.

EQUIPMENT USED

Infrared system	Dima	SMRO-0252	972127	02-06
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TESTRESULTS

Visual inspection: No detrimental effects were found.